

# FMV12N50ES

**FUJI POWER MOSFET** 

## Super FAP-E<sup>3S</sup> series

## **N-CHANNEL SILICON POWER MOSFET**

#### ■ Features

Maintains both low power loss and low noise Lower R<sub>DS</sub>(on) characteristic More controllable switching dv/dt by gate resistance Smaller V<sub>GS</sub> ringing waveform during switching Narrow band of the gate threshold voltage (3.7±0.5V) High avalanche durability

### Applications

Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

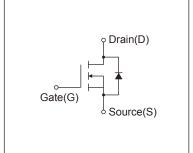
## Maximum Ratings and Characteristics

## ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

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TO-220F (SLS)  Lot No.  1rodemyr.  1pps nome.  12.2.2.2.2.2.2.3.4.2.2.2.3.4.2.2.2.3.4.2.2.2.3.4.2.2.2.3.4.2.2.2.3.4.2.2.2.3.4.2.2.2.3.4.2.2.2.3.4.2.2.2.3.4.2.2.2.3.4.2.2.2.3.4.2.2.2.3.4.2.2.3.4.2.2.2.2	15.0.2 2.70.2 2.70.2 2.70.2 2.70.2 2.70.2 2.70.2 2.70.2 2.70.2 2.70.2 2.70.2
①②③	CONNECTION ① GATE ② DRAIN ③ SOURCE

■ Outline Drawings [mm]

## **■** Equivalent circuit schematic



Description	Symbol	Characteristics	Unit	Remarks
Drain Sauras Valtara	V <sub>DS</sub>	500	V	
Drain-Source Voltage	V <sub>DSX</sub>	500	V	V <sub>GS</sub> = -30V
Continuous Drain Current	lο	±12	Α	
Pulsed Drain Current	IDP	±48	Α	
Gate-Source Voltage	V <sub>GS</sub>	±30	V	
Repetitive and Non-Repetitive Maximum Avalanche Current	Iar	12	Α	Note*1
Non-Repetitive Maximum Avalanche Energy	Eas	460.8	mJ	Note*2
Repetitive Maximum Avalanche Energy	Ear	6.5	mJ	Note*3
Peak Diode Recovery dV/dt	dV/dt	6.3	kV/μs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5
Maniana Barra Birainatian	PD	2.16	14/	Ta=25°C
Maximum Power Dissipation		65	W	Tc=25°C
O	Tch	150	°C	
Operating and Storage Temperature range	Tstg	-55 to + 150	°C	
Isolation Voltage	Viso	2	kVrms	t = 60sec_f = 60H

#### ● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions		min.	typ.	max.	Unit	
Drain-Source Breakdown Voltage	BVDSS	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	I <sub>D</sub> =250µA, V <sub>GS</sub> =0V		-	-	V	
Gate Threshold Voltage	V <sub>GS</sub> (th)	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>		3.2	3.7	4.2	V	
Zero Gate Voltage Drain Current		V <sub>DS</sub> =500V, V <sub>GS</sub> =0V	Cch=25°C	-	-	25		
	IDSS	V <sub>DS</sub> =400V, V <sub>GS</sub> =0V	<sub>ch</sub> =125°C	-	-	250	μA	
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		-	10	100	nA	
Drain-Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =6A, V <sub>GS</sub> =10V		-	0.427	0.50	Ω	
Forward Transconductance	g <sub>fs</sub>	I <sub>D</sub> =6A, V <sub>DS</sub> =25V		4.5	9	-	S	
Input Capacitance	Ciss	V <sub>DS</sub> =25V V <sub>GS</sub> =0V		-	1400	2100	pF	
Output Capacitance	Coss			-	160	240		
Reverse Transfer Capacitance	Crss	f=1MHz	-	11.5	17.5			
Turn-On Time	td(on)	V <sub>cc</sub> =300V V <sub>GS</sub> =10V I <sub>D</sub> =6A R <sub>G</sub> =15Ω		-	31	46.5	5 ns	
Turn-On Time	tr			-	18	27		
Turn-Off Time	td(off)			-	83	124.5		
	tf			-	16	27		
Total Gate Charge	Q <sub>G</sub>	V <sub>cc</sub> =250V I <sub>D</sub> =12A V <sub>cs</sub> =10V		-	43	56		
Gate-Source Charge	Q <sub>GS</sub>			-	13	23	nC	
Gate-Drain Charge	Q <sub>GD</sub>			-	14	21		
Gate-Drain Crossover Charge	Qsw			-	6	10		
Avalanche Capability	lav	L=2.44mH, Tch=25°C		12	-	-	Α	
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =12A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		-	0.86	1.30	V	
Reverse Recovery Time	trr	I <sub>F</sub> =12A, V <sub>GS</sub> =0V	I <sub>F</sub> =12A, V <sub>GS</sub> =0V		0.37	-	μs	
Reverse Recovery Charge	Qrr	-di/dt=100A/µs, Tch=25°C		-	5.0	-	μC	

#### Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to Case			1.920	°C/W
	Rth (ch-a)	Channel to Ambient			58.0	°C/W

Note \*1 : Tch≤150°C.

Note '2: Stating Tch=25°C, I<sub>AS</sub>=5A, L=33.8mH, Vcc=60V, R<sub>G</sub>=50Ω.

Eas limited by maximum channel temperature and avalanche current.

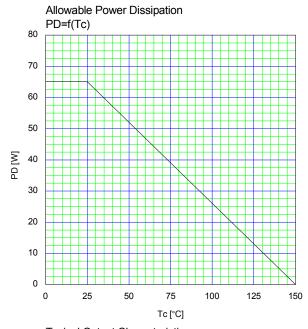
See to 'Avalanche Energy' graph.

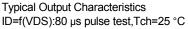
Note \*3 : Repetitive rating : Pulse width limited by maximum channel temperature.

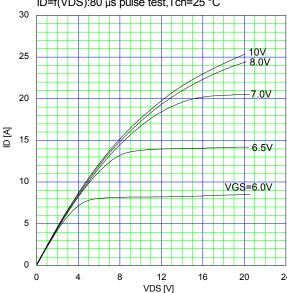
See to the 'Transient Themal impeadance' graph.

Note \*4 : Ir≤-Iɒ, -di/dt=100A/µs, Vcc≤BVbss, Tch≤150°C.

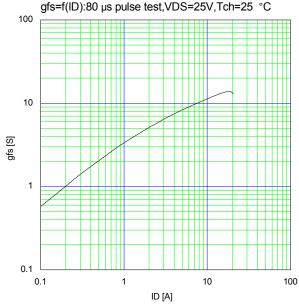
Note \*5 : Ir≤-Iɒ, dv/dt=6.3kV/µs, Vcc≤BVbss, Tch≤150°C.



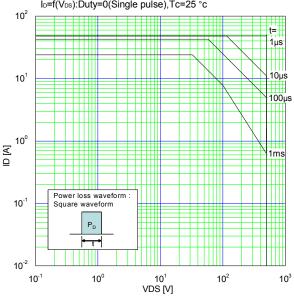




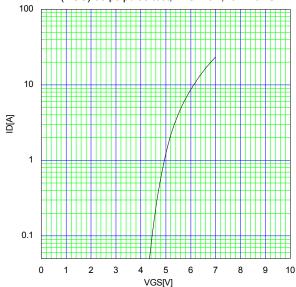
Typical Transconductance



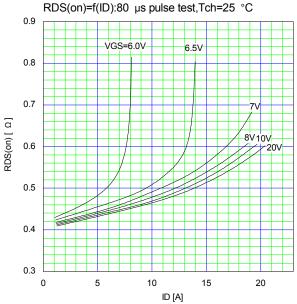
Safe Operating Area  $I_D=f(V_{DS})$ :Duty=0(Single pulse),Tc=25 °c

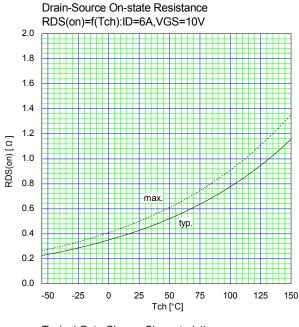


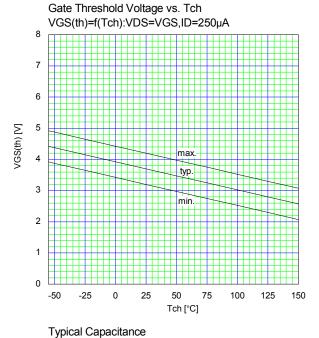
Typical Transfer Characteristic ID=f(VGS):80 µs pulse test,VDS=25V,Tch=25 °C

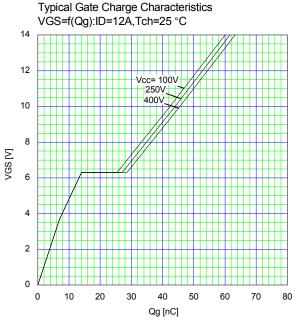


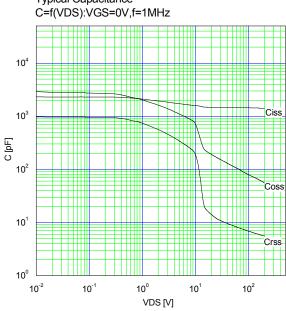
Typical Drain-Source on-state Resistance

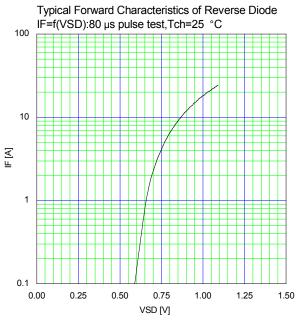


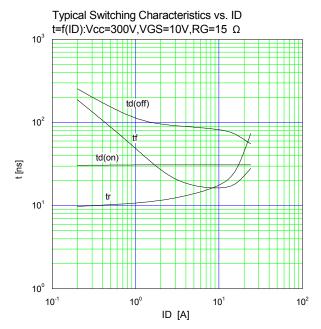


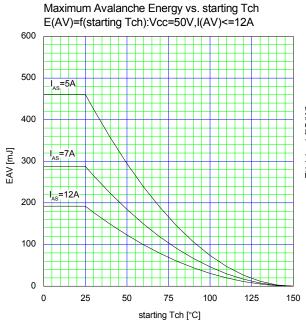


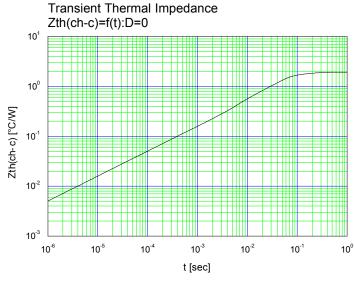












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